

ABSTRACT OF THE DISCLOSURE

A method of chemical mechanical polishing a wafer comprises: forming an optical property modifying layer on a surface of a feature of interest disposed on a wafer, removing material from the wafer using a chemical mechanical polishing process, directing light onto a surface of the wafer and using light reflected from a surface of the wafer to determine when the optical property modifying layer has been reached, and stopping the chemical mechanical polishing process in response to the determination that the optical property modifying layer has been reached. A wafer for use in manufacturing a magnetic recording head is also included. The wafer comprises a substrate, a pattern including an optical property modifying layer on a surface of a feature of interest supported by the substrate, and a dielectric layer positioned on the optical property modifying layer.